



IC Packaging Markets

2015/2016 Global Report Series

Complex multi-component and multi-layered packages have added a new dimension and cost to high speed performance to integrated circuits (ICs) in terms of their function and small form factor, thus making them game changers for the electronics manufacturing industry overall. It is the package of the IC which controls the device footprint to the printed circuit board (PCB), thereby enabling a multitude of small and new, handheld electronics computing and communicating IC devices to be invented and proliferate in today's emerging markets.

New Venture Research (NVR) is pleased to announce its continuing coverage of the IC packaging market with two new reports in 2015 and 2016, *The Worldwide IC Packaging Market–2015 Edition* and *Advanced IC Packaging Technologies, Materials, and Markets–2016 Edition*. Each report has a different focus, thus allowing the reader to analyze the world of IC packaging from a number of market perspectives, in a unique report that combines special information to meet individual market research needs.

The first report, *The Worldwide IC Packaging Market –2015 Edition*, presents NVR's annual forecast for each of the major package families by semiconductor product type (2014-2019). This information is then totaled and segmented in detail. The report also presents NVR's continuing, extensive coverage of the evolving outsourced assembly and test (OSAT) contractor market.

The second innovative report, *Advanced IC Packaging Technologies, Materials, and Markets–2016 Edition*, analyzes critical advanced IC packaging methods, primarily aimed at the mobile handheld consumer market, while also including some leading material analysis of IC packaging sets and design features.

The IC Packaging series will provide readers with an effective tool for assessing the future trends in this growing new market. Please review each report's summary Table of Contents on the following page for more detail.

Payment Method

Check in the amount of \$ _____ is enclosed.

Invoice per P.O. # _____

Please charge: Visa MasterCard American Express

Card # _____ Exp. _____

Name On Card _____

Signature _____ Date _____

Shipping Address

Name _____

Title _____

Company _____

Address _____

City/State/Zip _____

Telephone _____

Fax _____

E-mail _____

REPORT TITLE	PRICE	QTY	TOTAL
The Worldwide IC Packaging Market - 2015 Edition - single-user license (PDF Only)	\$3,995		
Advanced IC Packaging Technologies, Materials, and Markets - 2016 Edition single-user license (PDF Only)	\$3,995		
(Pre-Order Discount)	(\$1495)		
The Complete Series (both reports including discount)	\$6495		
Add Excel Spreadsheet of all tables for The Worldwide IC Packaging report \$1000			
Add Excel Spreadsheet of all tables for Advanced IC Packaging report \$1000			

Returns: No return privileges. **International Orders:** Must be prepaid, please contact us for payment arrangements.

New Venture Research

337 Clay St., Suite 101
Nevada City, CA 95959
Tel: (408) 244-1100 Fax: (530) 265-1998
www.newventureresearch.com; kwilliams@newventureresearch.com

Subtotal	
TOTAL	

The Worldwide IC Packaging Market - 2015 Edition

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: The State of the Industry

Chapter 4: Worldwide IC Packaging Market
Analysis and Forecasts - 2013-2019

Chapter 5: IC Package Market Analysis and
Forecasts by Semiconductor Device - 2013-2019

Chapter 6: IC Package Market Analysis and
Forecasts by Packaging Family - 2013-2019

Chapter 7: OSAT Market Analysis and Forecasts

Chapter 8: Company Profiles

Published July 2015, 400+ pages

Advanced IC Packaging Technologies, Materials, and Markets - 2016 Edition

Chapter 1: Introduction

Chapter 2: Executive Summary

Chapter 3: Overview of IC Packaging
Markets Worldwide

Chapter 4: Interconnection
Technologies

Chapter 5: Multichip Packages

Chapter 6: System-in-Package Solutions
& Substrate Materials

Chapter 7: Advanced Single-Chip
Packages

Chapter 8: Company Profiles

Published January 2016, 300+ pages

About the Author

Jerry Watkins is an independent senior analyst with more than 18 years of experience in the field of market research and consulting. He has worked for leading research companies such as Frost & Sullivan, Lucid Information Services, and NSI Research both in management and as a writer. Mr. Watkins has authored many syndicated reports, previously in the telecommunications sector and more recently in the computing, merchant embedded computing industry, as well as two IC packaging related reports in 2014/2015. He holds two university degrees including a B.A. in History, as well as a M.A. in International Studies.